

**VIA AND VIA LANDING STRUCTURES FOR SMOOTHING TRANSITIONS IN**  
**MULTI-LAYER SUBSTRATES**

**ABSTRACT OF THE DISCLOSURE**

5           An integrated circuit arrangement or package includes  
a set of contact pads arranged in a pattern and a multi-  
layer conductive structure, which electrically connects the  
set of contact pads to at least one signal line. The  
conductive structure provides impedance matching between  
10   the pads and the at least one signal line.